# Low-Voltage CMOS Octal Buffer Flow Through Pinout

# With 5 V-Tolerant Inputs and Outputs (3-State, Inverting)

The MC74LCX540 is a high performance, inverting octal buffer operating from a 2.3 to 3.6 V supply. This device is similar in function to the MC74LCX240, while providing flow through architecture. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_{\rm I}$  specification of 5.5 V allows MC74LCX540 inputs to be safely driven from 5 V devices. The MC74LCX540 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24 mA at the outputs. The Output Enable  $(\overline{OE1}, \overline{OE2})$  inputs, when HIGH, disables the outputs by placing them in a HIGH Z condition.

#### **Features**

- Designed for 2.3 to 3.6 V V<sub>CC</sub> Operation
- 5 V Tolerant Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- $I_{OFF}$  Specification Guarantees High Impedance When  $V_{CC} = 0 \text{ V}$
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA)
   Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
  - ♦ Human Body Model >2000 V
  - ♦ Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



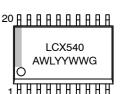
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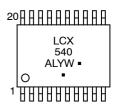


SOIC-20 WB DW SUFFIX CASE 751D





TSSOP-20 DT SUFFIX CASE 948E



A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

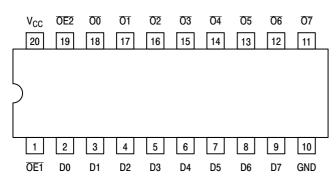


Figure 1. Pinout: 20-Lead (Top View)



Pins	Function		
<del>OEn</del>	Output Enable Inputs		
Dn	Data Inputs		
On	3-State Outputs		

# **TRUTH TABLE**

Inputs		Outputs	
OE1	OE2	Dn	On
L	L	L	Н
L	L	Н	L
Х	Н	Х	Z
Н	Х	Х	Z

- H = High Voltage Level
- L = Low Voltage Level
- Z = High Impedance State
- $X = High \text{ or Low Voltage Level and Transitions are Acceptable For I}_{CC}$  reasons, DO NOT FLOAT Inputs

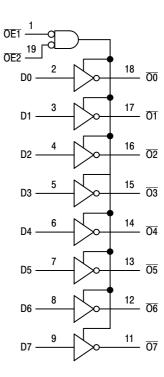


Figure 2. Logic Diagram

# **MAXIMUM RATINGS**

Symbol	Parameter	Condition	Value	Units
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_1 \le +7.0$	V
Vo	DC Output Voltage	Output in 3-State	$-0.5 \le V_0 \le +7.0$	V
		(Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	-50	mA
lok	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
		V <sub>O</sub> > V <sub>CC</sub>	+50	mA
Io	DC Output Source/Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State) (3-State)	0 0		V <sub>CC</sub> 5.5	V
I <sub>OH</sub>	HIGH Level Output Current, V <sub>CC</sub> = 3.0 V - 3.6 V			-24	mA
l <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 3.0 V - 3.6 V			24	mA
I <sub>OH</sub>	HIGH Level Output Current, V <sub>CC</sub> = 2.7 V - 3.0 V			-12	mA
l <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 2.7 V - 3.0 V			12	mA
T <sub>A</sub>	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, $V_{IN}$ from 0.8 V to 2.0 V, $V_{CC}$ = 3.0 V	0		10	ns/V

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX540DWR2G	SOIC-20 WB (Pb-Free)	1000 Tape & Reel
MC74LCX540DTG	TSSOP-20 (Pb-Free)	75 Units / Rail
MC74LCX540DTR2G	TSSOP-20 (Pb-Free)	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>1.</sup> Output in HIGH or LOW State. I<sub>O</sub> absolute maximum rating must be observed.

# DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = -40°C	to +85°C	
Symbol	Characteristic	Condition	Min	Max	Units
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0		V
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ I}_{OH} = -100 \mu\text{A}$	V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA	2.2		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	V
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	
I <sub>OZ</sub>	3-State Output Current	$V_{CC}$ = 3.6 V, $V_{IN}$ = $V_{IH}$ or $V_{IL}$ , $V_{OUT}$ = 0 to 5.5 V		±5	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>CC</sub> = 0, V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V		10	μΑ
I <sub>IN</sub>	Input Leakage Current	V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND		±5	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND		10	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

<sup>2.</sup> These values of  $V_{\parallel}$  are used to test DC electrical characteristics only.

# AC CHARACTERISTICS ( $t_R = t_F = 2.5 \text{ ns}$ ; $C_L = 50 \text{ pF}$ ; $R_L = 500 \Omega$ )

					Limits				
			TA	= -40°C to +8	35°C				
			V <sub>CC</sub> = 3.0	V to 3.6 V	V <sub>CC</sub> = 2.7 V	1			
Symbol	Parameter	Waveform	Min	Max	Max	Units			
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	7.5 7.5	ns			
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable Time to High and Low Level	2	1.5 1.5	8.5 8.5	9.5 9.5	ns			
t <sub>PHZ</sub>	Output Disable Time From High and Low Level	2	1.5 1.5	7.5 7.5	8.5 8.5	ns			
t <sub>OSHL</sub> t <sub>OSLH</sub>	Output-to-Output Skew (Note 3)			1.0 1.0		ns			

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

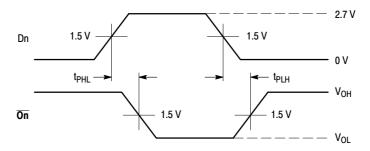
# **DYNAMIC SWITCHING CHARACTERISTICS**

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V
$V_{OLV}$	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V

<sup>4.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

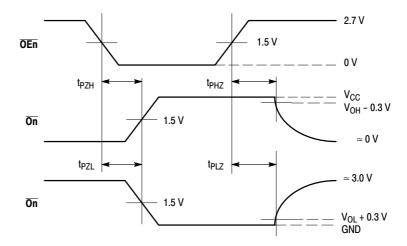
# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3V, $V_I$ = 0 V or $V_{CC}$	25	pF



#### **WAVEFORM 1 - PROPAGATION DELAYS**

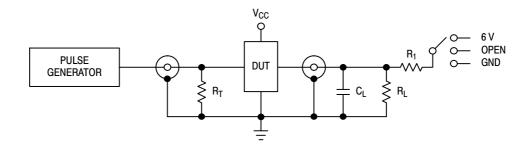
 $t_{R} = t_{F} = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_{W} = 500 \text{ ns}$ 



#### **WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES**

 $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%; f = 1 MHz;  $t_W$  = 500 ns

Figure 3. AC Waveforms



Test	Switch
t <sub>PLH</sub> , t <sub>PHL</sub>	Open
t <sub>PZL</sub> , t <sub>PLZ</sub>	6 V
Open Collector/Drain t <sub>PLH</sub> and t <sub>PHL</sub>	6 V
t <sub>PZH</sub> , t <sub>PHZ</sub>	GND

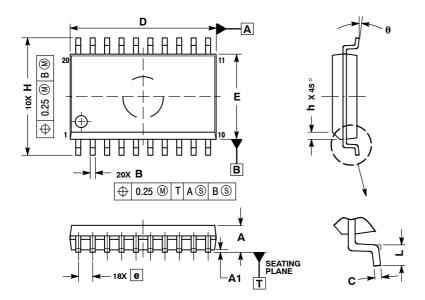
 $C_L$  = 50 pF or equivalent (Includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

# **PACKAGE DIMENSIONS**

SOIC-20 WB CASE 751D-05 ISSUE G



#### NOTES:

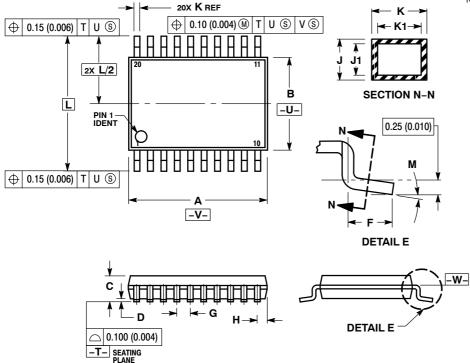
- NOTES:

  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN MAX			
Α	2.35 2.65			
A1	0.10 0.25			
В	0.35	0.49		
С	0.23 0.33			
D	12.65	12.95		
Е	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
θ	0°	7 °		

#### PACKAGE DIMENSIONS

#### TSSOP-20 CASE 948E-02 **ISSUE C**



16X 0.36

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

- MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE
  MOLD FLASH, PROTRUSIONS OR GATE
  BURRS. MOLD FLASH OR GATE BURRS
  SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE
  INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION
  SHALL NOT EXCEED 0.25 (0.01) DEP. SIDE.
- SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE
  DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL
- CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE —W—.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
_	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252 BSC	
М	0°	8°	0°	8°

# - 7.06 - 0.65 **PITCH**

DIMENSIONS: MILLIMETERS

16X 1.26

**SOLDERING FOOTPRINT** 

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